3.2mm x1.6mm SMD CHIP LED LAMP

APT3216SURC HYPER RED

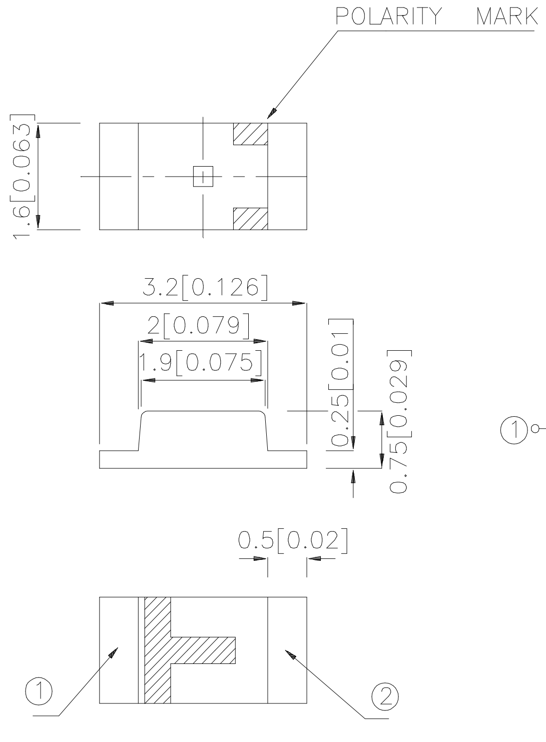
Features

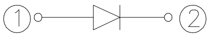
- ●3.2mmx1.6mm SMT LED, 0.75mm THICKNESS.
- ●LOW POWER CONSUMPTION.
- ●WIDE VIEWING ANGLE.
- ●IDEAL FOR BACKLIGHT AND INDICATOR.
- ●VARIOUS COLORS AND LENS TYPES AVAILABLE.
- ●PACKAGE : 2000PCS / REEL.
- ●RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions





Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.2(0.008") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2θ1/2
APT3216SURC	HYPER RED (InGaAlP)	WATER CLEAR	70	200	120°

Note:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

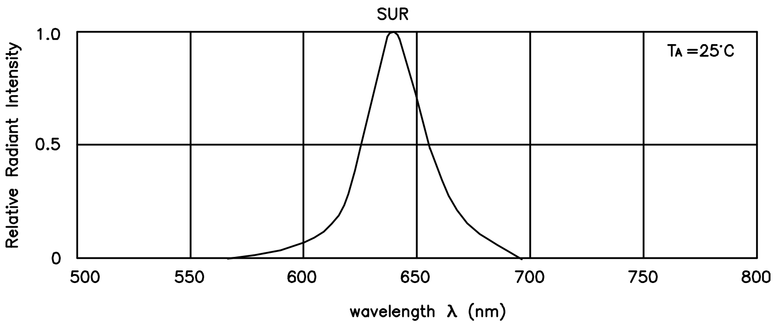
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	I_F=20mA
λD	Dominant Wavelength	Hyper Red	628		nm	I_F=20mA
$\Delta\lambda$1/2	Spectral Line Half-width	Hyper Red	27		nm	I_F=20mA
C	Capacitance	Hyper Red	45		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	Hyper Red	1.9	2.5	V	I_F=20mA
I_R	Reverse Current	Hyper Red		10	uA	V_R = 5V

Absolute Maximum Ratings at T_A=25°C

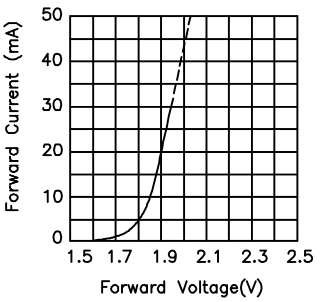
Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

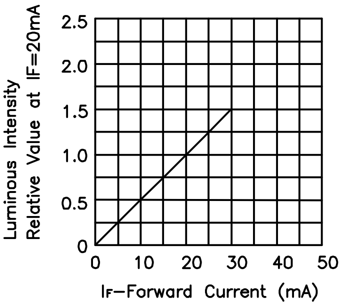


RELATIVE INTENSITY Vs. WAVELENGTH

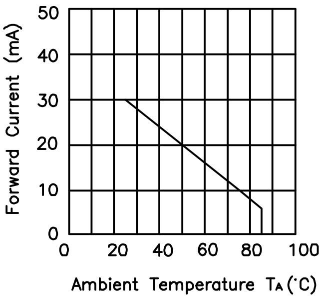
Hyper Red **APT3216SURC**



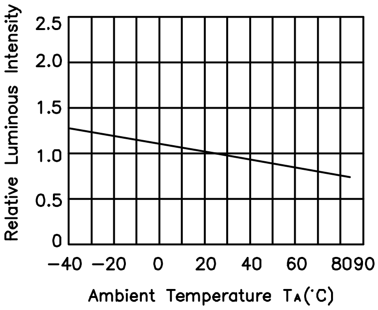
FORWARD CURRENT Vs. FORWARD VOLTAGE



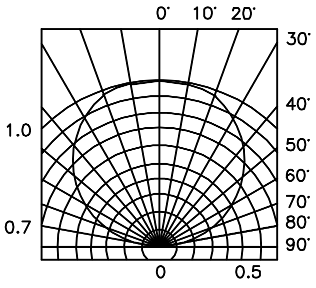
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE



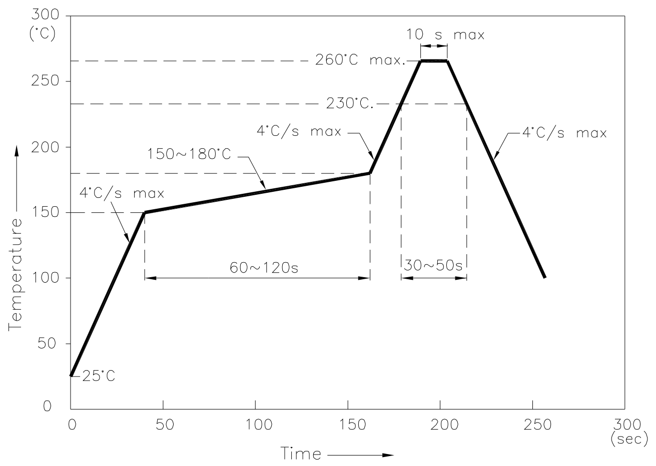
LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

APT3216SURC

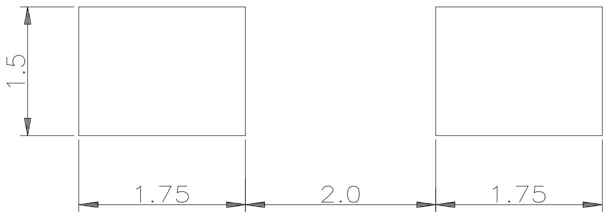
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/−5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern
(Units : mm)



Tape Specifications
(Units : mm)